compensated digital output
- Wide supply voltage range, from 2.4 V to 5.5 V
- I2C Interface with communication speeds up to 1 MHz and two user selectable addresses
- Typical accuracy of ± 1.5 %RH and ± 0.1 °C for SHT35
- Very fast start-up and measurement time
- Tiny 8-Pin DFN package

Product Summary

SHT3x-DIS is the next generation of Sensirion's temperature and humidity sensors. It builds on a new CMOSens® sensor chip that is at the heart of Sensirion's new humidity and temperature platform. The SHT3x-DIS has increased intelligence, reliability and improved accuracy specifications compared to its predecessor. Its functionality includes enhanced signal processing, two distinctive and user selectable I2C addresses and communication speeds of up to 1 MHz. The DFN package has a footprint of 2.5 x 2.5 mm^2 while keeping a height of 0.9 mm. This allows for integration of the SHT3x-DIS into a great variety of applications. Additionally, the wide supply voltage range of 2.4 V to 5.5 V guarantees compatibility with diverse assembly situations. All in all, the SHT3x-DIS incorporates 15 years of knowledge of Sensirion, the leader in the humidity sensor industry.

Benefits of Sensirion's CMOSens® Technology

- High reliability and long-term stability
- Industry-proven technology with a track record of more than 15 years
- Designed for mass production
- High process capability
- High signal-to-noise ratio

Content

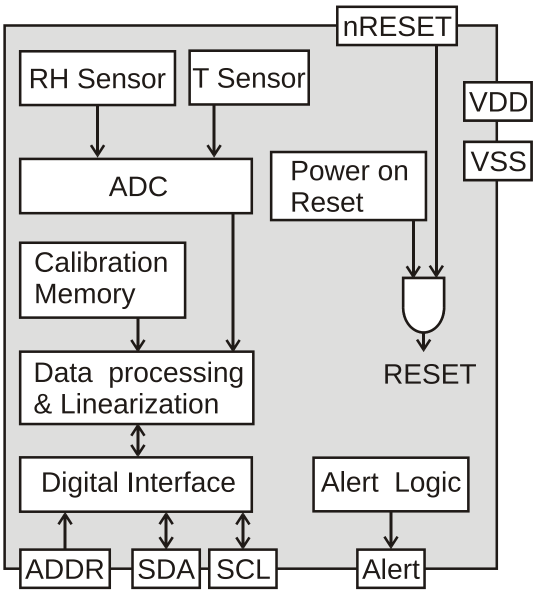

Figure 1 Functional block diagram of the SHT3x-DIS. The sensor signals for humidity and temperature are factory calibrated, linearized and compensated for temperature and supply voltage dependencies.

Parameter	Condition	Value	Units
SHT30 Accuracy tolerance[1]	Typ.	±2	%RH
	Max.	**Figure 2**	-
SHT31 Accuracy tolerance[1]	Typ.	±2	%RH
	Max.	**Figure 3**	-
SHT35 Accuracy tolerance[1]	Typ.	±1.5	%RH
	Max.	**Figure 4**	-
Repeatability[2]	Low	0.25	%RH
	Medium	0.15	%RH
	High	0.10	%RH
Resolution	Typ.	0.01	%RH
Hysteresis	at 25°C	±0.8	%RH
Specified range[3]	extended[4]	0 to 100	%RH
Response time[5]	$\tau_{63\%}$	8[6]	s
Long-term drift	Typ.[7]	<0.25	%RH/yr

Table 1 Humidity sensor specification.

Temperature Sensor Specification

Parameter	Condition	Value	Units
SHT30 Accuracy tolerance[1]	typ., 0°C to 65°C	±0.2	°C
SHT31 Accuracy tolerance[1]	typ., 0°C to 90°C	±0.2	°C
SHT35 Accuracy tolerance[1]	typ., 20°C to 60°C	±0.1	°C
Repeatability[2]	Low	0.24	°C
	Medium	0.12	°C
	High	0.06	°C
Resolution	Typ.	0.015	°C
Specified Range	-	-40 to 125	°C
Response time [8]	$\tau_{63\%}$	>2	s
Long Term Drift	max	<0.03	°C/yr

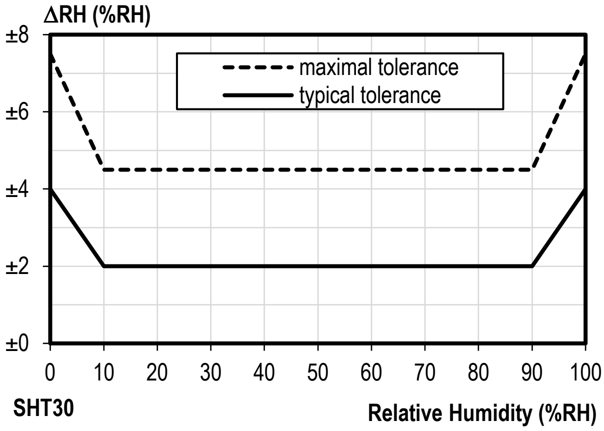

Figure 2 Tolerance of RH at 25°C for SHT30.

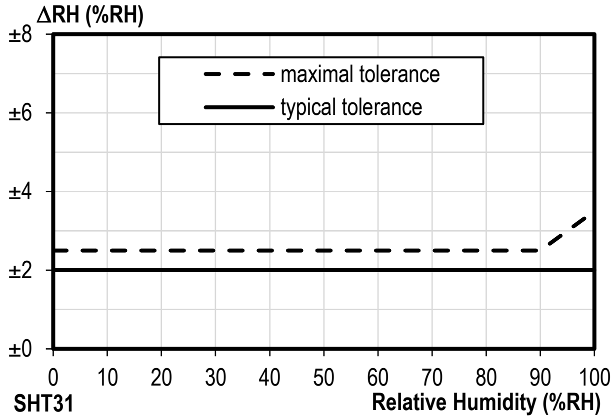

Figure 3 Tolerance of RH at 25°C for SHT31.

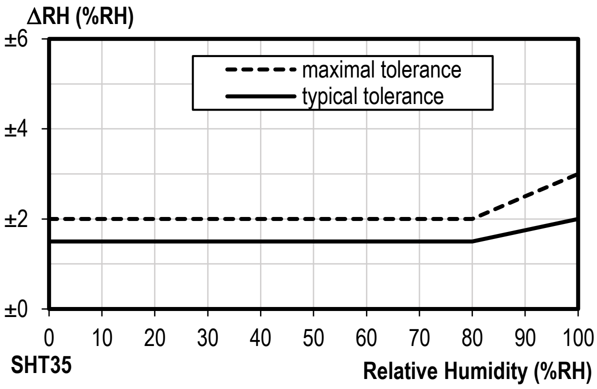

Figure 4 Tolerance of RH at 25°C for SHT35.

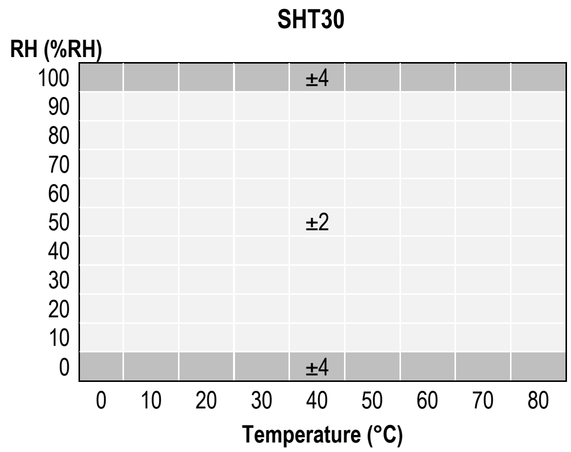

Figure 5 Typical tolerance of RH over T for SHT30.

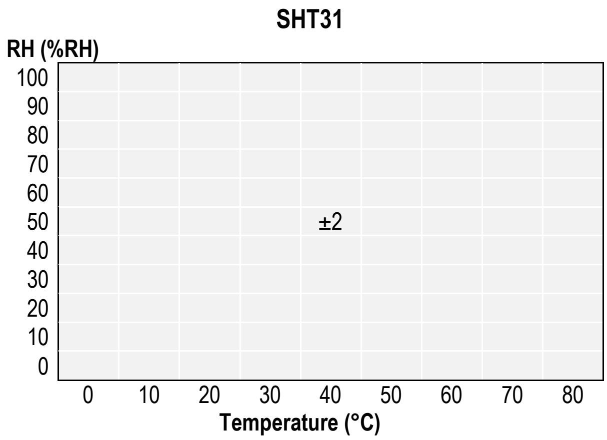

Figure 6 Typical tolerance of RH over T for SHT31.

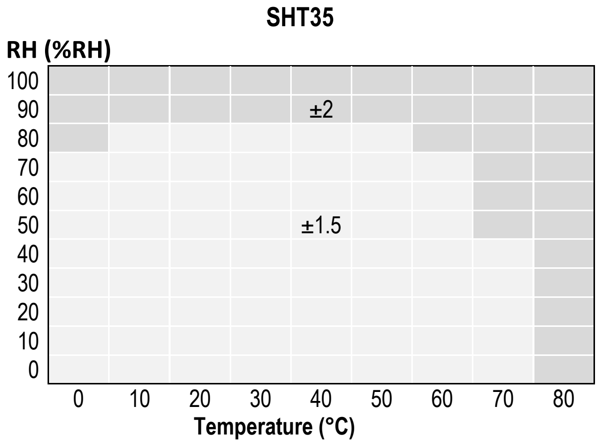

Figure 7 Typical tolerance of RH over T for SHT35.

Temperature Sensor Performance Graphs

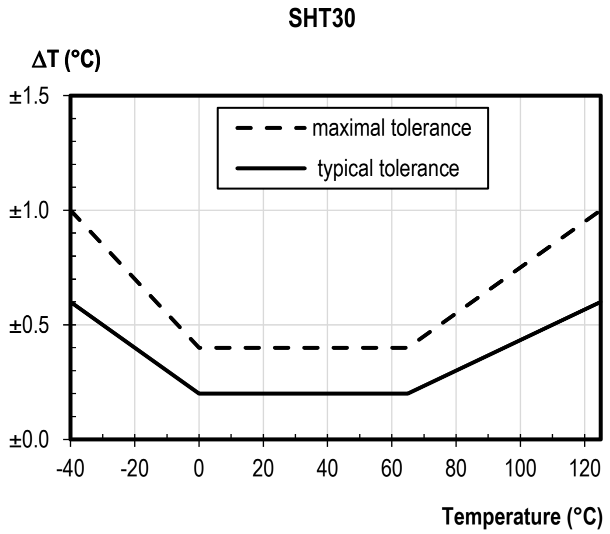

Figure 8 Temperature accuracy of the SHT30 sensor.

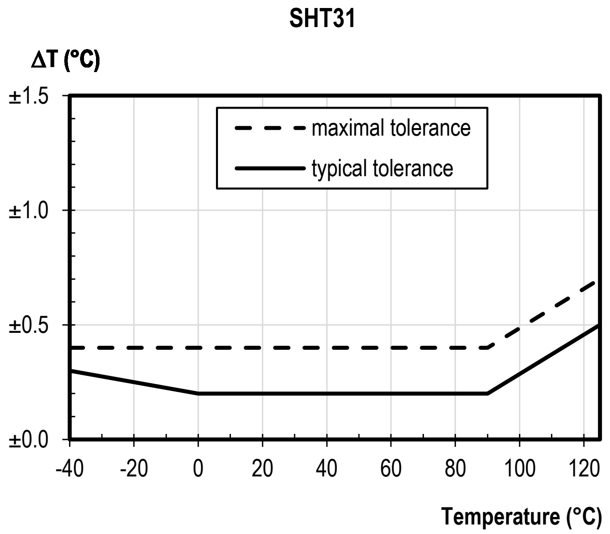

Figure 9 Temperature accuracy of the SHT31 sensor.

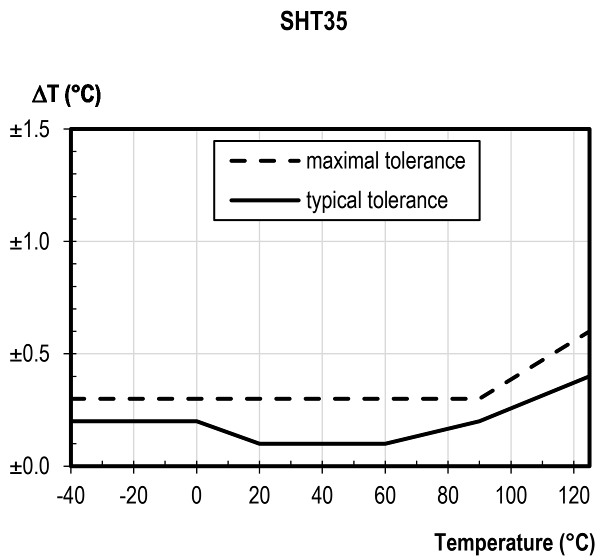

Figure 10 Temperature accuracy of the SHT35 sensor.

3 Pin Assignment

The SHT3x-DIS comes in a tiny 8-pin DFN package – see Table 6.

Pin	Name	Comments
1	SDA	Serial data; input / output
2	ADDR	Address pin; input; connect to either logic high or low, do not leave floating
3	ALERT	Indicates alarm condition; output; must be left floating if unused
4	SCL	Serial clock; input / output
5	VDD	Supply voltage; input
6	nRESET	Reset pin active low; input; if not used it is recommended to be left floating; can be connected to VDD with a series resistor of R ≥2 kΩ
7	R	No electrical function; to be connected to VSS
8	VSS	Ground

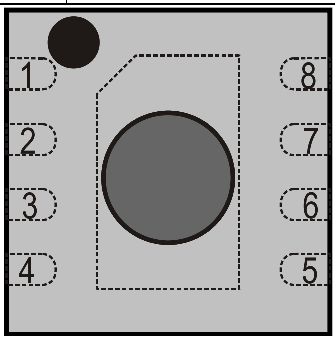

Table 6 SHT3x-DIS pin assignment (transparent top view). Dashed lines are only visible if viewed from below. The die pad is internally connected to VSS.

3.1 Power Pins (VDD, VSS)

The electrical specifications of the SHT3x-DIS are shown in Table 3. The power supply pins must be decoupled with a 100 nF capacitor that shall be placed as close to the sensor as possible – see Figure 11 for a typical application circuit.

3.2 Serial Clock and Serial Data (SCL, SDA)

SCL is used to synchronize the communication between microcontroller and the sensor. The clock frequency can be freely chosen between 0 to 1000 kHz. Commands with clock stretching according to I2C Standard[11] are supported.

The SDA pin is used to transfer data to and from the sensor. Communication with frequencies up to 400 kHz must meet the I2C *Fast Mode*[11] standard. Communication frequencies up to 1 Mhz are supported following the specifications given in **Table 20**.

Both SCL and SDA lines are open-drain I/Os with diodes to VDD and VSS. They should be connected to external pull-up resistors (please refer to Figure 11). A device on the I2C bus must only drive a line to ground. The external pull-up resistors (e.g. R_p=10 kΩ) are required to pull the signal high. For dimensioning resistor sizes please take bus capacity and communication frequency into account (see for example Section 7.1 of NXPs I2C Manual for more details[11]). It should be noted that pull-up resistors may be included in I/O circuits of microcontrollers. It is recommended to wire the sensor according to the application circuit as shown in Figure 11.

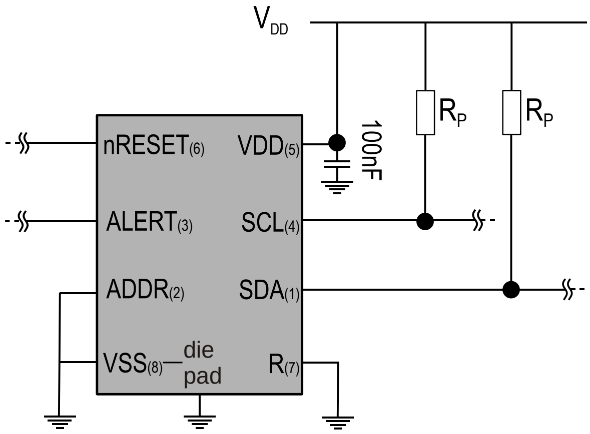

Figure 11 Typical application circuit. Please note that the positioning of the pins does not reflect the position on the real sensor. This is shown in Table 6.

3.3 Die Pad (center pad)

The die pad or center pad is visible from below and located in the center of the package. It is electrically connected to VSS. Hence electrical considerations do not impose constraints on the wiring of the die pad. However, due to mechanical reasons it is recommended to solder the center pad to the PCB. For more information on design-in, please refer to the document "SHTxx Design Guide".

3.4 ADDR Pin

Through the appropriate wiring of the ADDR pin the I2C address can be selected (see Table 7 for the respective addresses). The ADDR pin can either be connected to logic high or logic low. The address of the sensor can be changed dynamically during operation by switching the level on the ADDR pin. The only constraint is that the level has to stay constant starting from the I2C start condition until the communication is finished. This allows to connect more than two SHT3x-DIS onto the same bus.

The repeatability setting influences the measurement duration and thus the overall energy consumption of the sensor. This is explained in section 2.

Condition		Hex. code	
Repeatability	Clock stretching	MSB	LSB
High	enabled	0x2C	06
Medium			0D
Low			10
High	disabled	0x24	00
Medium			0B
Low			16
e.g. 0x2C06: high repeatability measurement with clock stretching enabled			

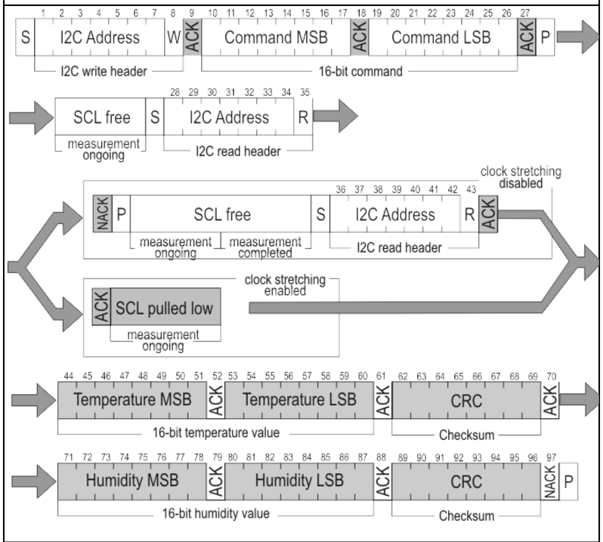

Table 8 Measurement commands in single shot mode (Clear blocks are controlled by the microcontroller, grey blocks by the sensor).

4.4 Readout of Measurement Results for Single Shot Mode

After the sensor has completed the measurement, the master can read the measurement results (pair of RH& T) by sending a START condition followed by an I2C read header. The sensor will acknowledge the reception of the read header and send two bytes of data (temperature) followed by one byte CRC checksum and another two bytes of data (relative humidity) followed by one byte CRC checksum. Each byte must be acknowledged by the microcontroller with an ACK condition for the sensor to continue sending data. If the sensor does not receive an ACK from the master after any byte of data, it will not continue sending data.

The sensor will send the temperature value first and then the relative humidity value. After having received the checksum for the humidity value a NACK and stop condition should be sent (see Table 8).

The I2C master can abort the read transfer with a NACK condition after any data byte if it is not interested in subsequent data, e.g. the CRC byte or the second measurement result, in order to save time.

In case the user needs humidity and temperature data but does not want to process CRC data, it is recommended to read the two temperature bytes of data with the CRC byte (without processing the CRC data); after having read the two humidity bytes, the read transfer can be aborted with a with a NACK.

No Clock Stretching

When a command without clock stretching has been issued, the sensor responds to a read header with a not acknowledge (NACK), if no data is present.

Clock Stretching

When a command with clock stretching has been issued, the sensor responds to a read header with an ACK and subsequently pulls down the SCL line. The SCL line is pulled down until the measurement is complete. As soon as the measurement is complete, the sensor releases the SCL line and sends the measurement results.

4.5 Measurement Commands for Periodic Data Acquisition Mode

In this mode one issued measurement command yields *a stream of data pairs*. Each data pair consists of one 16 bit temperature and one 16 bit humidity value (in this order).

In periodic mode different measurement commands can be selected. The corresponding 16 bit commands are shown in Table 9. They differ with respect to repeatability (low, medium and high) and data acquisition frequency (0.5, 1, 2, 4 & 10 measurements per second, mps). Clock stretching cannot be selected in this mode.

The data acquisition frequency and the repeatability setting influences the measurement duration and the current consumption of the sensor. This is explained in section 2 of this datasheet.

If a measurement command is issued, while the sensor is busy with a measurement (measurement durations see Table 4), it is recommended to issue a break command first (see section 4.8). Upon reception of the break command the sensor will finish the ongoing measurement and enter the single shot mode.

Condition		Hex. code	
Repeatability	mps	MSB	LSB
High	0.5	0x20	32
Medium			24
Low			2F
High	1	0x21	30
Medium			26
Low			2D
High	2	0x22	36
Medium			20
Low			2B
High	4	0x23	34
Medium			22
Low			29
High	10	0x27	37
Medium			21
Low			2A
e.g. 0x2130: 1 high repeatability mps - measurement per second			

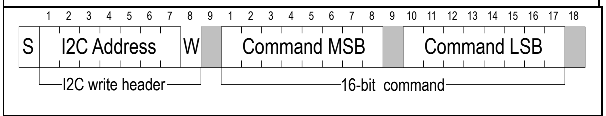

Table 9 Measurement commands for periodic data acquisition mode (Clear blocks are controlled by the microcontroller, grey blocks by the sensor). N.B.: At the highest mps setting self-heating of the sensor might occur.

4.6 Readout of Measurement Results for Periodic Mode

Transmission of the measurement data can be initiated through the fetch data command shown in Table 10. If no measurement data is present the I2C read header is responded with a NACK (Bit 9 in Table 10) and the communication stops. After the read out command fetch data has been issued, the data memory is cleared, i.e. no measurement data is present.

Command	Hex code
Fetch Data	0x E0 00

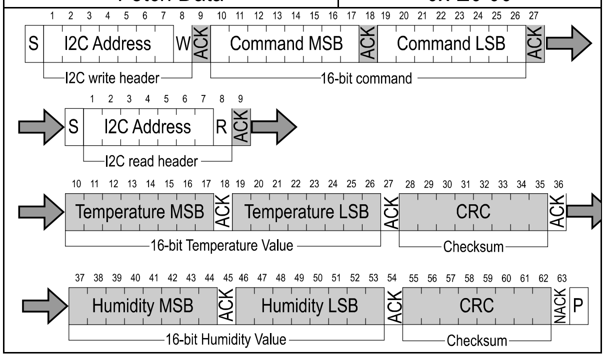

Table 10 Fetch Data command (Clear blocks are controlled by the microcontroller, grey blocks by the sensor).

4.7 ART Command

The ART (accelerated response time) feature can be activated by issuing the command in Table 11. After issuing the ART command the sensor will start acquiring data with a frequency of 4Hz.

The ART command is structurally similar to any other command in Table 9. Hence section 4.5 applies for starting a measurement, section 4.6 for reading out data and section 4.8 for stopping the periodic data acquisition.

The ART feature can also be evaluated using the Evaluation Kit EK-H5 from Sensirion.

Command	Hex Code
Periodic Measurement with ART	0x2B32

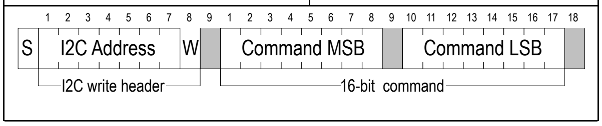

Table 11 Command for a periodic data acquisition with the ART feature (Clear blocks are controlled by the microcontroller, grey blocks by the sensor).

4.8 Break command / Stop Periodic Data Acquisition Mode

The periodic data acquisition mode can be stopped using the break command shown in Table 12. It is recommended to stop the periodic data acquisition prior to sending another command (except Fetch Data command) using the break command. Upon reception of the break command the sensor enters the single shot mode, after finishing the ongoing measurement. This can take up to 15 ms, depending on the selected repeatability.

Command	Hex Code
Break	0x3093

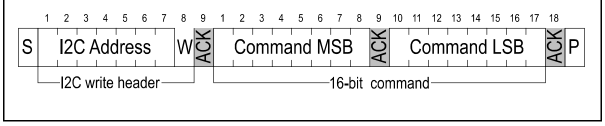

Table 12 Break command (Clear blocks are controlled by the microcontroller, grey blocks by the sensor).

4.9 Reset

A system reset of the SHT3x-DIS can be generated externally by issuing a command (soft reset) or by sending a pulse to the dedicated reset pin (nReset pin). Additionally, a system reset is generated internally during power-up. During the reset procedure the sensor will not process commands.

In order to achieve a full reset of the sensor without removing the power supply, it is recommended to use the nRESET pin of the SHT3x-DIS.

Interface Reset

If communication with the device is lost, the following signal sequence will reset the serial interface: While leaving SDA high, toggle SCL nine or more times. This must be followed by a Transmission Start sequence preceding the next command. This sequence resets the interface only. The status register preserves its content.

Soft Reset / Re-Initialization

The SHT3x-DIS provides a soft reset mechanism that forces the system into a well-defined state without removing the power supply. When the system is in idle state the soft reset command can be sent to the SHT3x-DIS. This triggers the sensor to reset its system controller and reloads calibration data from the memory. In order to start the soft reset procedure the command as shown in Table 13 should be sent.

It is worth noting that the sensor reloads calibration data prior to every measurement by default.

Command	Hex Code
Soft Reset	0x30A2

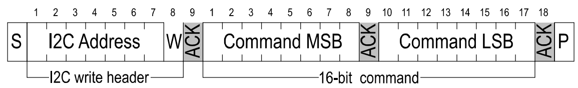

Table 13 Soft reset command (Clear blocks are controlled by the microcontroller, grey blocks by the sensor).

Reset through General Call

Additionally, a reset of the sensor can also be generated using the "general call" mode according to I2C-bus specification[12]. This generates a reset which is functionally identical to using the nReset pin. It is important to understand that a reset generated in this way is not device specific. All devices on the same I2C bus that support the general call mode will perform a reset. Additionally, this command only works when the sensor is able to process I2C commands. The appropriate command consists of two bytes and is shown in Table 14.

Reset through the nReset Pin

Pulling the nReset pin low (see Table 6) generates a reset similar to a hard reset. The nReset pin is internally connected to VDD through a pull-up resistor and hence active low. The nReset pin has to be pulled low for a minimum of 1 μs to generate a reset of the sensor.

Command	Code
Address byte	0x00
Second byte	0x06
Reset command using the general call address	0x0006

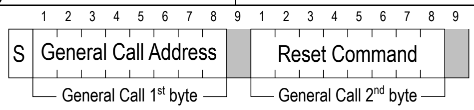

Table 14 Reset through the general call address (Clear blocks are controlled by the microcontroller, grey blocks by the sensor).

Hard Reset

A hard reset is achieved by switching the supply voltage to the VDD Pin off and then on again. In order to prevent powering the sensor over the ESD diodes, the voltage to pins 1 (SDA), 4 (SCL) and 2 (ADDR) also needs to be removed.

4.10 Heater

The SHT3x is equipped with an internal heater, which is meant for plausibility checking only. The temperature increase achieved by the heater depends on various parameters and lies in the range of a few degrees centigrade. It can be switched on and off by command, see table below. The status is listed in the status register. After a reset the heater is disabled (default condition).

Command	Hex Code	
	MSB	LSB
Heater Enable	0x30	6D
Heater Disabled		66

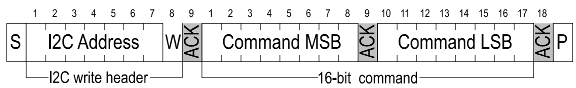

Table 15 Heater command (Clear blocks are controlled by the microcontroller, grey blocks by the sensor).

4.11 Status Register

The status register contains information on the operational status of the heater, the alert mode and on the execution status of the last command and the last write sequence. The command to read out the status register is shown in Table 16 whereas a description of the content can be found in Table 17.

Command	Hex code
Read Out of status register	0xF32D

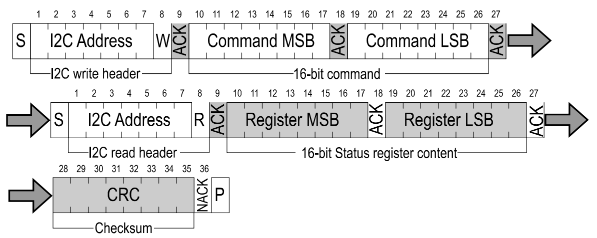

Table 16 Command to read out the status register (Clear blocks are controlled by the microcontroller, grey blocks by the sensor).

Bit	Field description	Default value
15	Alert pending status '0': no pending alerts '1': at least one pending alert	'1'
14	Reserved	'0'
13	Heater status '0' : Heater OFF '1' : Heater ON	'0'
12	Reserved	'0'
11	RH tracking alert '0' : no alert '1' . alert	'0
10	T tracking alert '0' : no alert '1' . alert	'0'
9:5	Reserved	'xxxxx'
4	System reset detected '0': no reset detected since last 'clear status register' command '1': reset detected (hard reset, soft reset command or supply fail)	'1'
3:2	Reserved	'00'
1	Command status '0': last command executed successfully '1': last command not processed. It was either invalid, failed the integrated command checksum	'0'
0	Write data checksum status '0': checksum of last write transfer was correct '1': checksum of last write transfer failed	'0'

Table 17 Description of the status register.

Clear Status Register

All flags (Bit 15, 11, 10, 4) in the status register can be cleared (set to zero) by sending the command shown in Table 18.

Command	Hex Code
Clear status register	0x 30 41

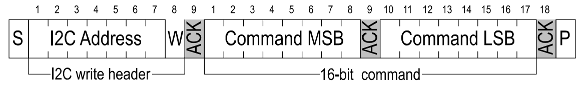

Table 18 Command to clear the status register (Clear blocks are controlled by the microcontroller, grey blocks by the sensor).

4.12 Checksum Calculation

The 8-bit CRC checksum transmitted after each data word is generated by a CRC algorithm. Its properties are displayed in Table 19. The CRC covers the contents of the two previously transmitted data bytes. To calculate the checksum only these two previously transmitted data bytes are used.

Property	Value
Name	CRC-8
Width	8 bit
Protected data	read and/or write data
Polynomial	0x31 ($x^8 + x^5 + x^4 + 1$)
Initialization	0xFF
Reflect input	False
Reflect output	False
Final XOR	0x00
Examples	CRC (0xBEEF) = 0x92

Table 19 I2C CRC properties.

4.13 Conversion of Signal Output

Measurement data is always transferred as 16-bit values (unsigned integer). These values are already linearized and compensated for temperature and supply voltage effects. Converting those raw values into a physical scale can be achieved using the following formulas.

Relative humidity conversion formula (result in %RH):

$$RH = 100 \cdot \frac{S_{RH}}{2^{16} - 1}$$

Temperature conversion formula (result in °C & °F):

$$T[°C] = -45 + 175 \cdot \frac{S_T}{2^{16} - 1}$$

$$T[°F] = -49 + 315 \cdot \frac{S_T}{2^{16} - 1}$$

S_{RH} and S_T denote the raw sensor output for humidity and temperature, respectively. The formulas work only correctly when S_{RH} and S_T are used in decimal representation.

4.14 Communication Timing

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units	Comments
SCL clock frequency	f_{SCL}		0	-	1000	kHz	
Hold time (repeated) START condition	$t_{HD;STA}$	After this period, the first clock pulse is generated	0.24	-	-	µs	
LOW period of the SCL clock	t_{LOW}		0.65	-	-	µs	
HIGH period of the SCL clock	t_{HIGH}		0.26	-	-	µs	
SDA hold time	$t_{HD;DAT}$		0	-	250	ns	Transmitting data
			0	-	-	ns	Receiving data
SDA set-up time	$t_{SU;DAT}$		100	-	-	ns	
SCL/SDA rise time	t_R		-	-	300	ns	
SCL/SDA fall time	t_F		-	-	300	ns	
SDA valid time	$t_{VD;DAT}$		-	-	0.9	µs	
Set-up time for a repeated START condition	$t_{SU;STA}$		0.6	-	-	µs	
Set-up time for STOP condition	$t_{SU;STO}$		0.6	-	-	µs	
Capacitive load on bus line	CB		-	-	400	pF	
Low level input voltage	V_{IL}		0	-	$0.3xV_{DD}$	V	
High level input voltage	V_{IH}		$0.7xV_{DD}$	-	$1xV_{DD}$	V	
Low level output voltage	V_{OL}	3 mA sink current	-	-	0.66	V	

Table 20 Communication timing specifications for I2C fm (fast mode), specifications are at 25°C and typical VDD. The numbers above are values according to the I2C Specification (UM10204, Rev. 6, April 4, 2014).

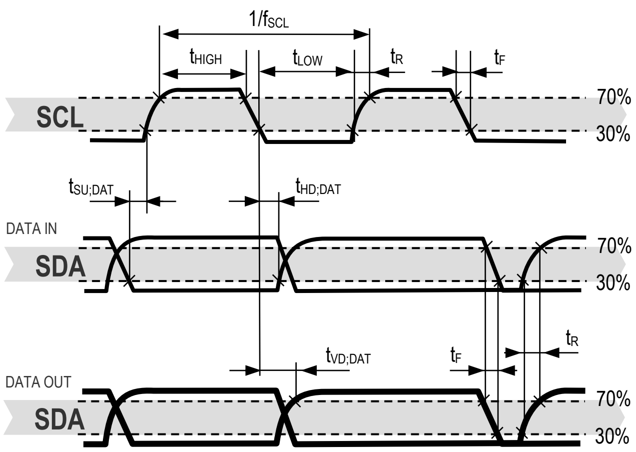

Figure 12 Timing diagram for digital input/output pads. SDA directions are seen from the sensor. Bold SDA lines are controlled by the sensor, plain SDA lines are controlled by the micro-controller. Note that SDA valid read time is triggered by falling edge of preceding toggle.

5.2 Package Outline

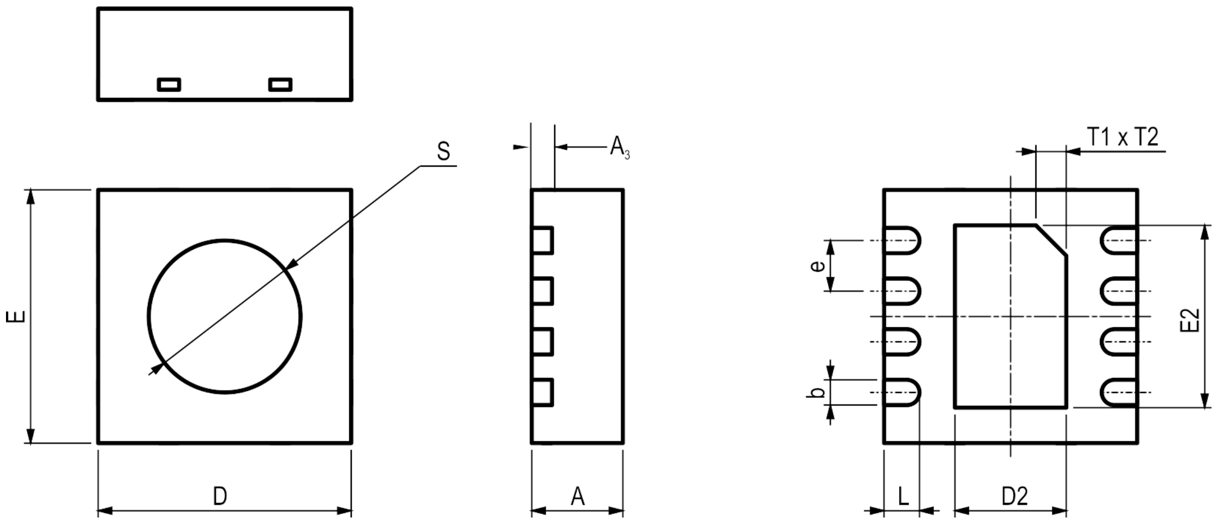

Figure 14 Dimensional drawing of SHT3x-DIS sensor package

Parameter	Symbol	Min	Nom.	Max	Units	Comments
Package height	A	0.8	0.9	1	mm	
Leadframe height	A3	-	0.2	-	mm	
Pad width	b	0.2	0.25	0.3	mm	
Package width	D	2.4	2.5	2.6	mm	
Center pad length	D2	1	1.1	1.2	mm	
Package length	E	2.4	2.5	2.6	mm	
Center pad width	E2	1.7	1.8	1.9	mm	
Pad pitch	e	-	0.5		mm	
Pad length	L	0.25	0.35	0.45	mm	
Max cavity	S	-	-	1.5	mm	Only as guidance. This value includes all tolerances, including displacement tolerances. Typically the opening will be smaller.
Center pad marking	T1xT2	-	0.3x45°	-	mm	indicates the position of pin 1

Table 21 Package outline.

5.3 Land Pattern

Figure 15 shows the land pattern. The land pattern is understood to be the open metal areas on the PCB, onto which the DFN pads are soldered.

The solder mask is understood to be the insulating layer on top of the PCB covering the copper traces. It is recommended to design the solder pads as a Non-Solder Mask Defined (NSMD) type. For NSMD pads, the solder mask opening should provide a 60 μm to 75 μm design clearance between any copper pad and solder mask. As the pad pitch is only 0.5 mm we recommend to have one solder mask opening for all 4 I/O pads on one side.

For solder paste printing it is recommended to use a laser-cut, stainless steel stencil with electro-polished trapezoidal walls and with 0.1 or 0.125 mm stencil thickness. The length of the stencil apertures for the I/O pads should be the same as the PCB pads. However, the position of the stencil apertures should have an offset of 0.1 mm away from the center of the package. The die pad aperture should cover about 70 – 90 % of the die pad area –thus it should have a size of about 0.9 mm x 1.6 mm.

For information on the soldering process and further recommendation on the assembly process please consult the Application Note HT_AN_SHTxx_Assembly_of_SMD_Packages , which can be found on the Sensirion webpage.

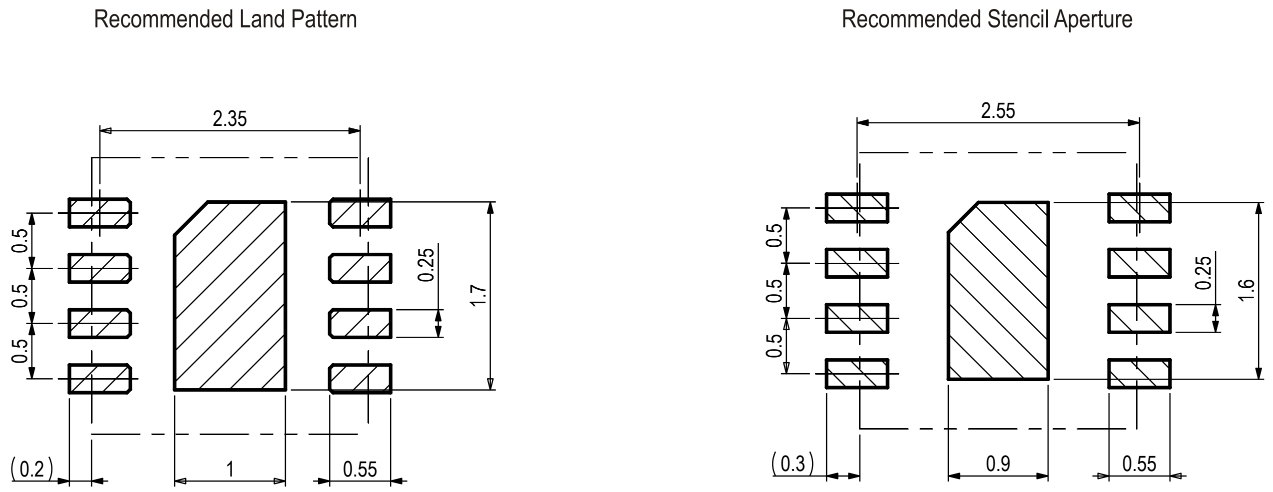

Figure 15 Recommended metal land pattern (left) and stencil apertures (right) for SHT3x-DIS. The dashed lines represent the outer dimension of the DFN package. The PCB pads (left) and stencil apertures (right) are indicated through the shaded areas.

6 Shipping Package

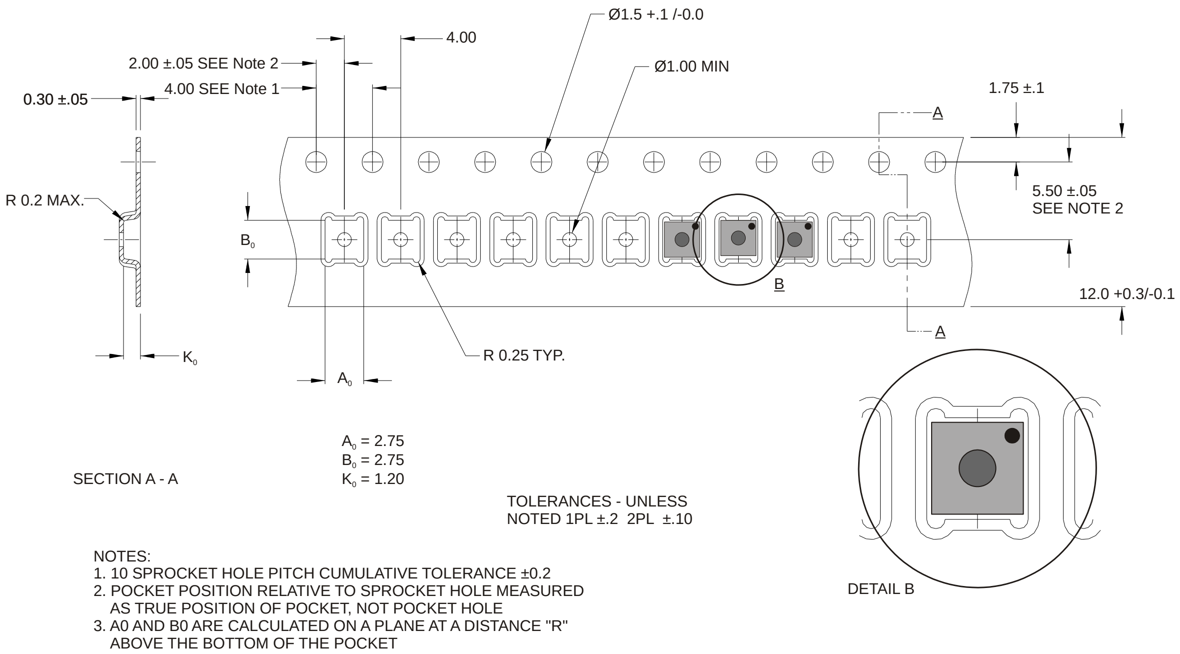

Figure 16 Technical drawing of the packaging tape with sensor orientation in tape. Header tape is to the right and trailer tape to the left on this drawing. Dimensions are given in millimeters.